



**GP**  
**ELECTRONICS**

**GPA4406**

**30V N-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
30V	6m $\Omega$ @10V	15A
	9m $\Omega$ @4.5V	

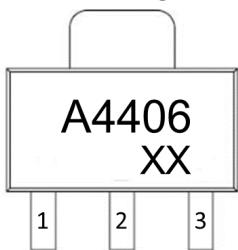
### Feature

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

### Application

- Power Switching Application

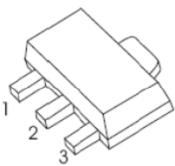
### MARKING:



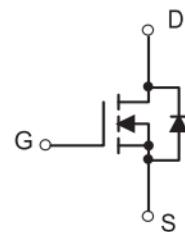
A4406= Device Code

XX = Date Code

**SOT-89-3L**



**Schematic diagram**



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	30	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	15	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	60	A
Power Dissipation <sup>5</sup>	$P_D$	3.5	W
Thermal Resistance from Junction to Ambient <sup>6</sup>	$R_{\theta JA}$	35.7	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55~+150	°C

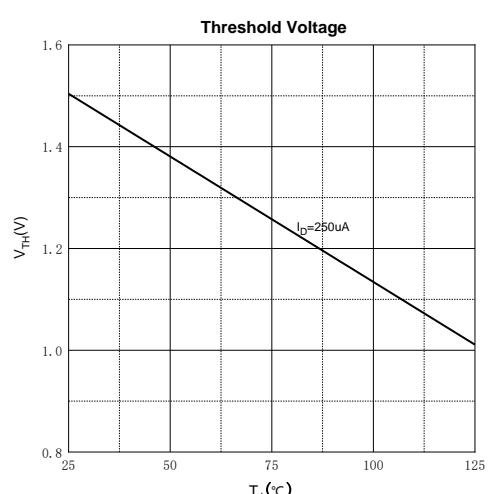
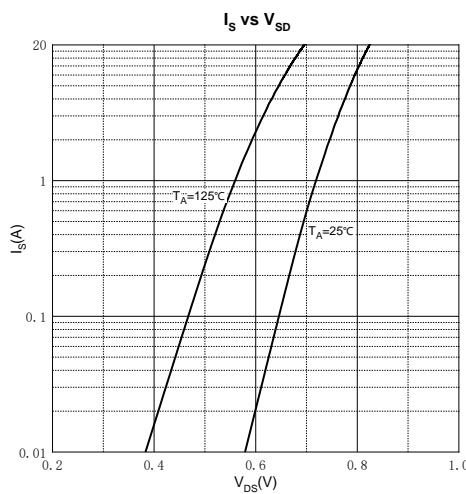
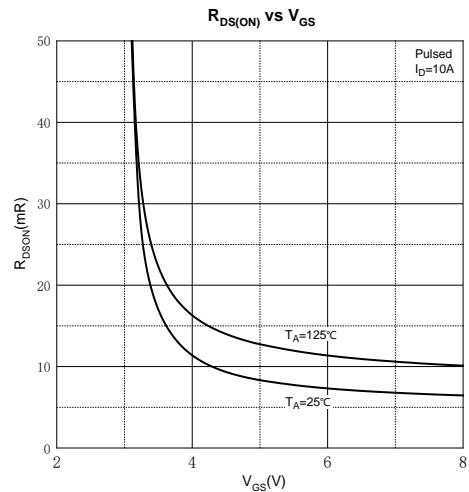
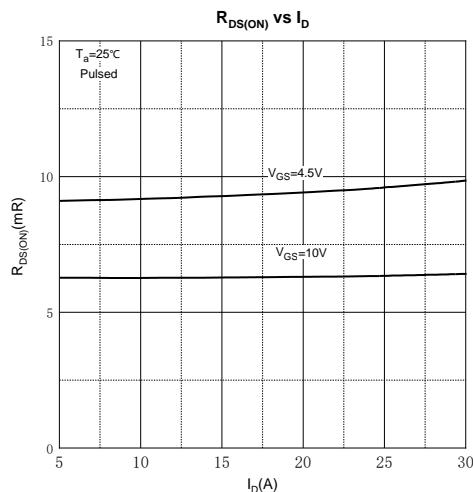
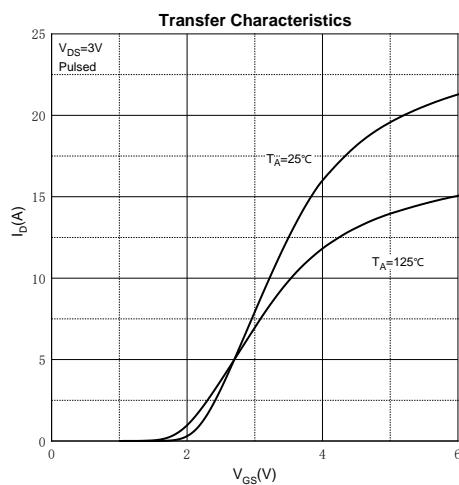
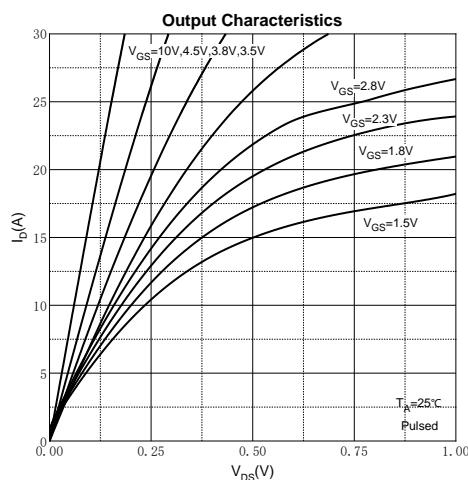
**MOSFET ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$  unless otherwise noted)**

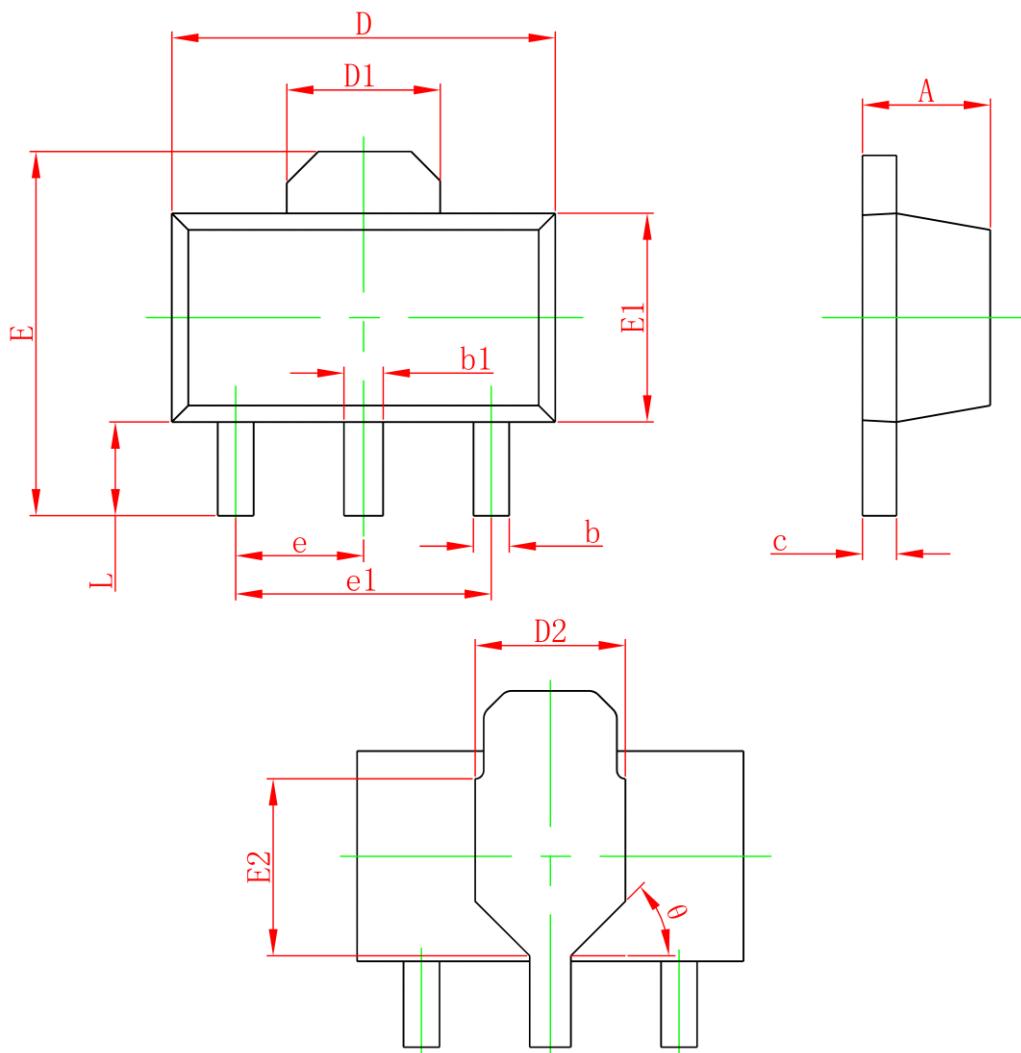
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.5	3.0	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 12\text{A}$		6	11	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 10\text{A}$		9	15	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1\text{MHz}$		990.2		pF
Output Capacitance	$C_{oss}$			143.7		
Reverse Transfer Capacitance	$C_{rss}$			128.2		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$		1.95		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 15V, V_{GS} = 4.5V, I_D = 10\text{A}$		22.2		nC
Gate-source Charge	$Q_{gs}$			3.0		
Gate-drain Charge	$Q_{gd}$			4.3		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 15V, V_{GS} = 10V, R_L = 15\Omega$ $R_G = 6\Omega$		11		ns
Turn-on Rise Time	$t_r$			12		
Turn-off Delay Time	$t_{d(\text{off})}$			36		
Turn-off Fall Time	$t_f$			10		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_s = 10\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu\text{s}$ , duty cycle  $\leq 1\%$ .
- 3.E<sub>AS</sub> condition:  $V_{DD} = 15V, V_{GS} = 10V, L = 0.5\text{mH}, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Characteristics



**SOT-89-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.380	0.580	0.015	0.023
c	0.350	0.500	0.014	0.020
D	4.400	4.600	0.173	0.181
D1	1.650REF		0.065REF	
D2	1.650	1.850	0.065	0.073
E	3.900	4.400	0.154	0.173
E1	2.300	2.600	0.091	0.102
E2	1.900REF		0.075REF	
e	1.500TYP		0.059TYP	
e1	3.000TYP		0.118TYP	
L	0.900	1.200	0.035	0.047
θ	45°		45°	